

Electronic Patent Application Fee Transmittal

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| Application Number: | 10633839 |
| Filing Date: | 04-Aug-2003 |
| Title of Invention: | SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER |
| First Named Inventor/Applicant Name: | Pavel N. Laptev |
| Filer: | Sheldon R. Meyer/Patricia Diehl |
| Attorney Docket Number: | TEGL-01212US1 |

Filed as Small Entity

Utility Filing Fees

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

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|----------------------------------------|------|---|-----|-----|
| Utility Appl Issue fee | 2501 | 1 | 700 | 700 |
| Publ. Fee- early, voluntary, or normal | 1504 | 1 | 300 | 300 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|---------------------------|----------|----------|--------|----------------------|
| Extension-of-Time: | | | | |
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 1000 |